

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ100N03LS G	**Issued**	06. May 2021
MA#	MA001321310		
Package	PG-TSDSON-8-1	**Weight***	36.06 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.709	1.97	1.97	19659	19659
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		66	
	non noble metal	zinc	7440-66-6	0.009	0.03		263	
	non noble metal	iron	7439-89-6	0.189	0.53		5252	
	non noble metal	copper	7440-50-8	7.689	21.33	21.90	213252	218833
wire	non noble metal	copper	7440-50-8	0.039	0.11	0.11	1095	1095
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1040	
	plastics	epoxy resin	-	1.930	5.35		53541	
	inorganic material	silicondioxide	60676-86-0	16.774	46.53	51.98	465237	519818
leadfinish	non noble metal	tin	7440-31-5	0.370	1.03	1.03	10264	10264
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2241	2241
solder	non noble metal	tin	7440-31-5	0.021	0.06		579	
	noble metal	silver	7440-22-4	0.026	0.07		723	
	non noble metal	lead	7439-92-1	0.996	2.76	2.89	27629	28931
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		109	
	non noble metal	iron	7439-89-6	0.078	0.22		2173	
	non noble metal	copper	7440-50-8	3.182	8.82	9.05	88247	90556
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			33	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2606	
	non noble metal	copper	7440-50-8	3.816	10.58	10.85	105834	108603
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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